
Bluetooth Module Datasheet

Model: SJR-BTM350

Version: V1.1

2021-11-21

Sky Jiarun Technologies Co., Ltd.

Tel: (0755)85279490

E-mail: sales@tianjiarun.com

Web: www.tianjiarun.com

Baoan, Shenzhen

List of Contents

1 Introduction	3
2 Key Features	3
3 Applications	4
4 Block Diagram	4
5 General specifications	4
6 Module Package Information	5
6.1 Pinout Diagram and package dimensions	5
6.2 Module Pin descriptions	6
7 Electrical Characteristics	10
7.1 Absolute Maximum Ratings	10
7.2 Recommended Operating Conditions	10
8 Recommended reflow temperature profile	11

1 Introduction

Sky Jiarun Technologies introduces the pioneer of the Bluetooth 5.2 modules SJR-BTM350 which is a high performance, cost effective, low power and compact solution. The Bluetooth module provides a complete 2.4GHz Bluetooth system based on the QCC3050 BGA chipset which is a single chip radio and baseband IC for Bluetooth 2.4GHz systems. This module is fully qualified single-chip dual mode Bluetooth@v5.2 system.

2 Key Features

BTM350(QCC3050) Features

- Qualified to Bluetooth v5.2 specification
- Dual 120 MHz Qualcomm® Kalimba™ audio DSPs
- 32/80 MHz Developer Processor for applications
- Firmware Processor for system
- Flexible QSPI flash programmable platform
- High-performance 24bit audio interface
- Digital and analog microphone interfaces
- Flexible PIO controller and LED pins with PWM support
- Serial interfaces: UART, Bit Serializer (I² C/SPI), USB 2.0
- Advanced audio algorithms
- Active Noise Cancellation: Hybrid, Feedforward, and Feedback modes, using Digital or Analog Mics, enabled using license keys available from Qualcomm®
- Qualcomm® aptX™ and aptX HD Audio
- 1 or 2 mic Qualcomm® cVc™ headset speech processing
- Integrated PMU: Dual SMPS for system/digital circuits, Integrated Li-ion battery charger

Application subsystem

- Dual-core application subsystem 32/80 MHz operation
- 32-bit Firmware Processor (reserved for system use) executes:
 - Bluetooth upper stack
 - Profiles
 - House-keeping code
- 32-bit Developer Processor executes: Developer applications
- 64 Mb flash memory
- On-chip caches per core enable optimized performance and power consumption

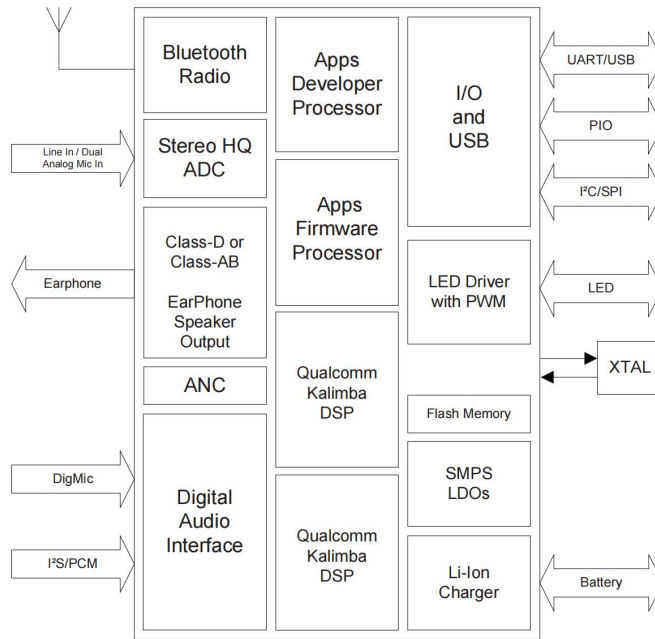
Bluetooth subsystem

- Qualified to Bluetooth v5.2 specification including 2 Mbps Bluetooth Low Energy and Bluetooth Low Energy Isochronous Channels
- Qualcomm® Bluetooth High Speed Link
- Single ended antenna connection with on-chip balun and Tx/Rx switch
- Bluetooth, Bluetooth Low Energy, and mixed topologies supported
- Class 1 support

3 Applications

- Qualcomm TrueWireless™ stereo earbuds
- Bluetooth USB Source application

4 Block Diagram

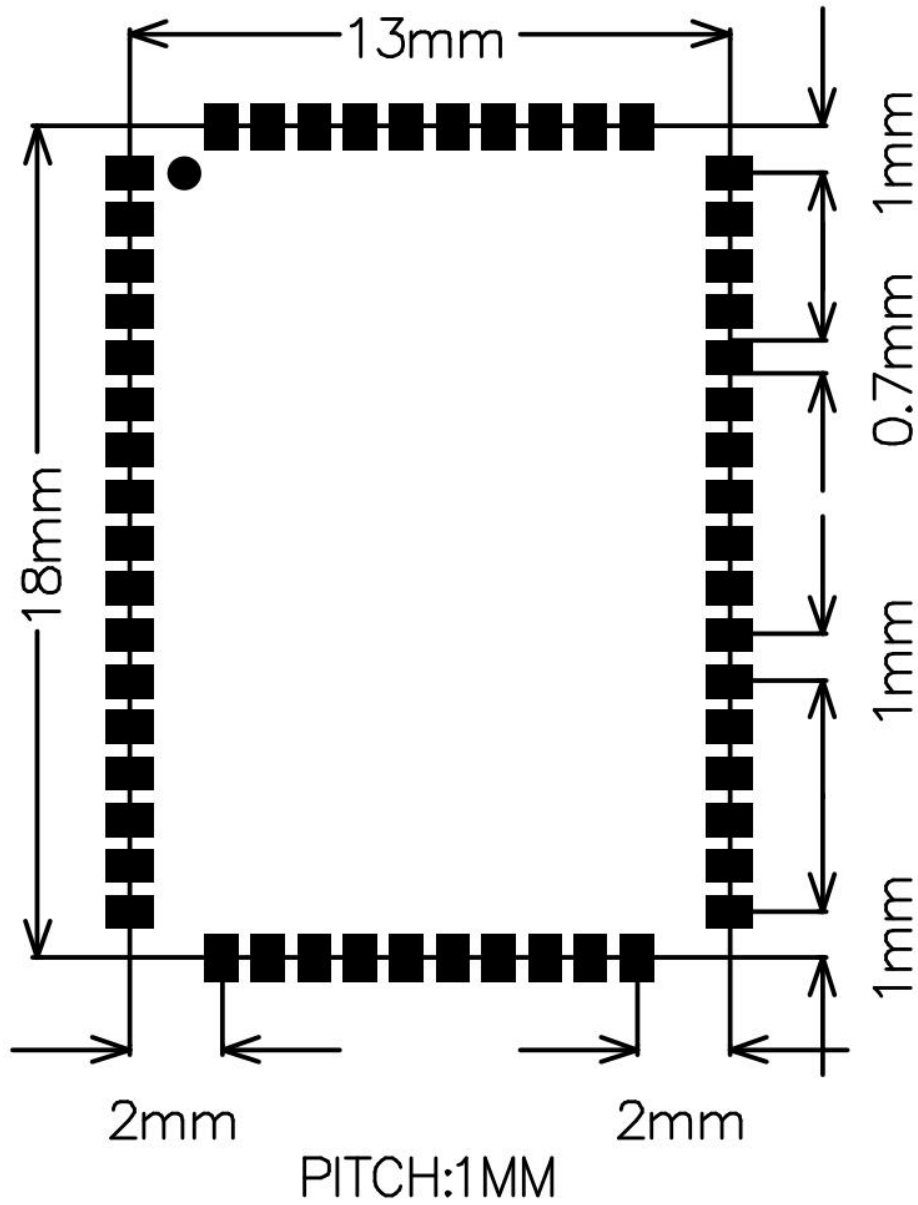


5 General specifications

Model Name	SJR-BTM350
Product Description	Bluetooth 5.2 Class1.5 Module
Bluetooth Standard	Bluetooth 5.2
Chipset	QCC3050 BGA
Dimension	13mm x 18mm x 2.5mm
Operating Conditions	
Voltage	2.8~4.3V
Temperature	-40~+85°C
Storage Temperature	-40~+85°C
Electrical Specifications	
Frequency Range	2402~2480MHz
Maximum RF Transmit Power	9dBm
$\pi/4$ DQPSK Receive Sensitivity	-93dBm
8DPSK Receive Sensitivity	-87dBm

6 Module Package Information

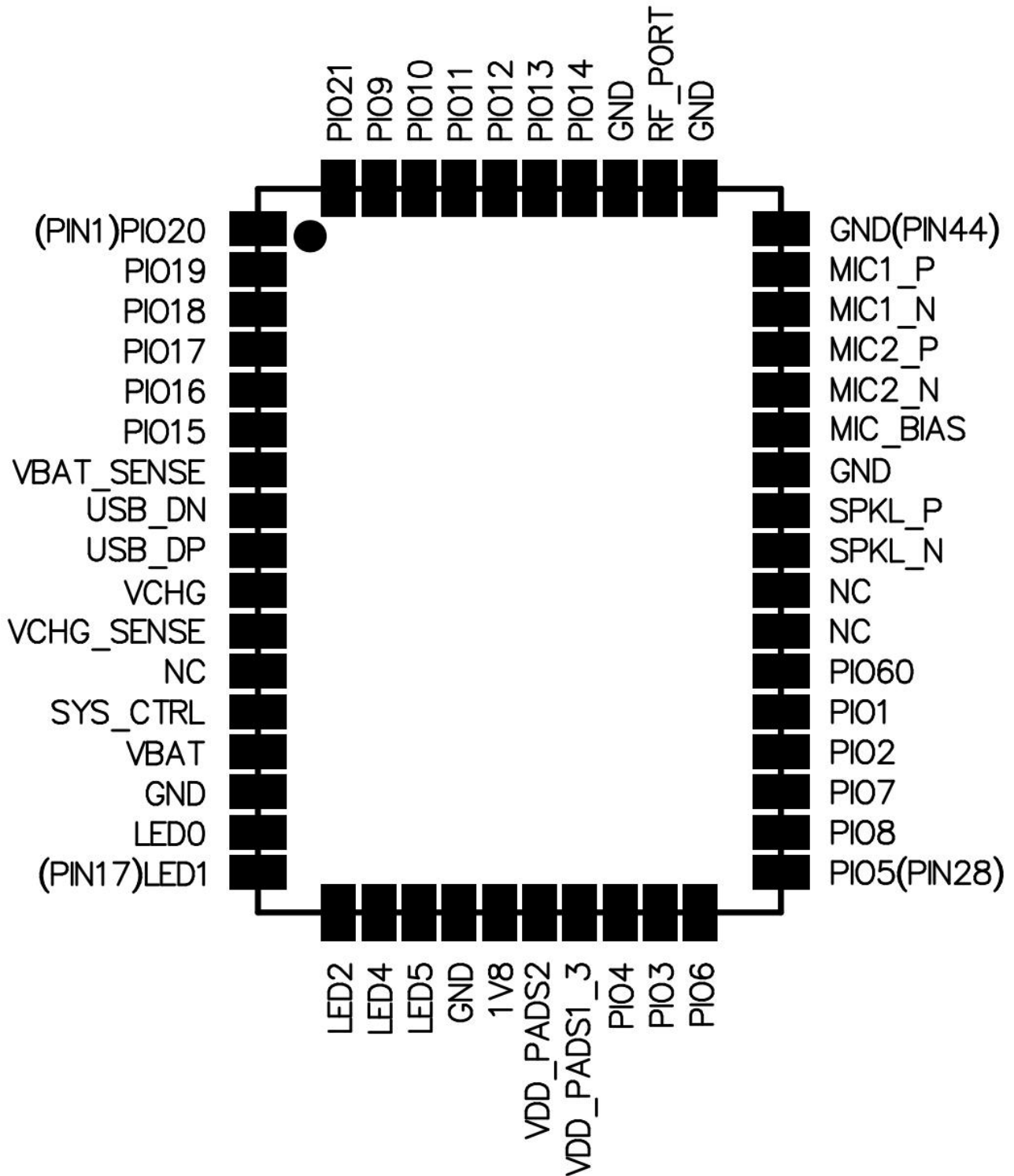
6.1 Pinout Diagram and package dimensions



Unit: MM

Recommended PCB layout footprint

6.2 Module Pin descriptions



Pin#	Pin Name	Pin type	Description
1	PIO[20]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 20.
2	PIO[19]	Digital: Bidirectional with programmable strength internal	Programmable I/O line 19.

		pull- up/pull-down	
3	PIO[18]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 18.
4	PIO[17]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 17.
5	PIO[16]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 16.
6	PIO[15]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 15.
7	VBAT_SENSE	Analog	Charger input sense pin.
8	USB_DN	Digital	USB Full Speed device D- I/O. IEC-61000-4-2 (device level) ESD Protection
9	USB_DP	Digital	USB Full Speed device D+ I/O. IEC-61000-4-2 (device level) ESD Protection
10	VCHG	Supply	Charger input to Bypass regulator.
11	VCHG_SENSE	Analog	Charger input sense pin after external mode sense-resistor. High impedance. NOTE If using internal charger or no charger, connect VCHG_SENSE direct to VCHG.
12	NC	NC	NC
13	SYS_CTRL	Digital input	Typically connected to an ON/OFF push button. Boots device in response to a button press when power is still present from battery and/or charger but software has placed the device in the OFF or DORMANT state. Additionally useable as a digital input in normal operation. No pull. Additional function: PIO[0] input only
14	VBAT	Supply	Battery voltage input.
15	GND	Ground	Ground
16	AIO[0]/LED[0]	Analog or digital input/ open drain output.	General-purpose analog/digital input or open drain LED output.
17	AIO[1]/LED[1]	Analog or digital input/ open drain output.	General-purpose analog/digital input or open drain LED output.
18	AIO[2]/LED[2]	Analog or digital input/ open drain output.	General-purpose analog/digital input or open drain LED output.
19	AIO[4]/LED[4]	Analog or digital input/ open drain output.	General-purpose analog/digital input or open drain LED output.
20	AIO[5]/LED[5]	Analog or digital input/ open drain output.	General-purpose analog/digital input or open drain LED output.

21	GND	Ground	Ground
22	1V8	Supply	1.8V voltage output.
23	VDD_PADS_2	Supply	1.8 V/3.3 V PIO supply.
24	VDD_PADS1_3	Supply	1.8 V/3.3 V PIO supply.
25	PIO[4]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 4. Alternative function: TBR_MOSI[1]
26	PIO[3]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 3. Alternative function: TBR_MISO[2]
27	PIO[6]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 6. Alternative function: TBR_MOSI[0]
28	PIO[5]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 5. Alternative function: TBR_MISO[1]
29	PIO[8]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 8. Alternative function: TBR_CLK
30	PIO[7]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 7. Alternative function: TBR_MISO[0]
31	PIO[2]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 2. Alternative function: TBR_MISO[3]
32	PIO[1]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Automatically defaults to RESET# mode when the device is unpowered, or in off modes. Reconfigurable as a PIO after boot. Alternative function: Programmable I/O line 1
33	PIO[60]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 60.
34	NC	NC	NC
35	NC	NC	NC
36	AUDIO_HPL_N/ SPKL_N	Analog	Headphone/speaker differential left output, negative. Alternative function: Differential left line output, negative
37	AUDIO_HPL_P/ SPKL_P	Analog	Headphone/speaker differential left output, positive. Alternative function: Differential left line output, positive
38	GND	Ground	Ground
39	AUDIO_MIC_BIAS	Analog	Mic bias output.
40	AUDIO_MIC2_N/ LINEIN_R_N	Analog	Microphone differential 2 input, negative.

			Alternative function: Differential audio line input right, negative
41	AUDIO_MIC2_P/ LINEIN_R_P	Analog	Microphone differential 2 input, positive. Alternative function: Differential audio line input right, positive
42	AUDIO_MIC1_N/ LINEIN_L_N	Analog	Microphone differential 1 input, negative. Alternative function: Differential audio line input left, negative
43	AUDIO_MIC1_P/ LINEIN_L_P	Analog	Microphone differential 1 input, positive. Alternative function: Differential audio line input left, positive
44	GND	Ground	Ground
45	GND	Ground	Ground
46	BT_RF	RF	Bluetooth transmit/receive.
47	GND	Ground	Ground
48	PIO[14]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 14.
49	PIO[13]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 13.
50	PIO[12]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 12.
51	PIO[11]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 11.
52	PIO[10]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 10.
53	PIO[9]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 9.
54	PIO[21]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 21.

7 Electrical Characteristics

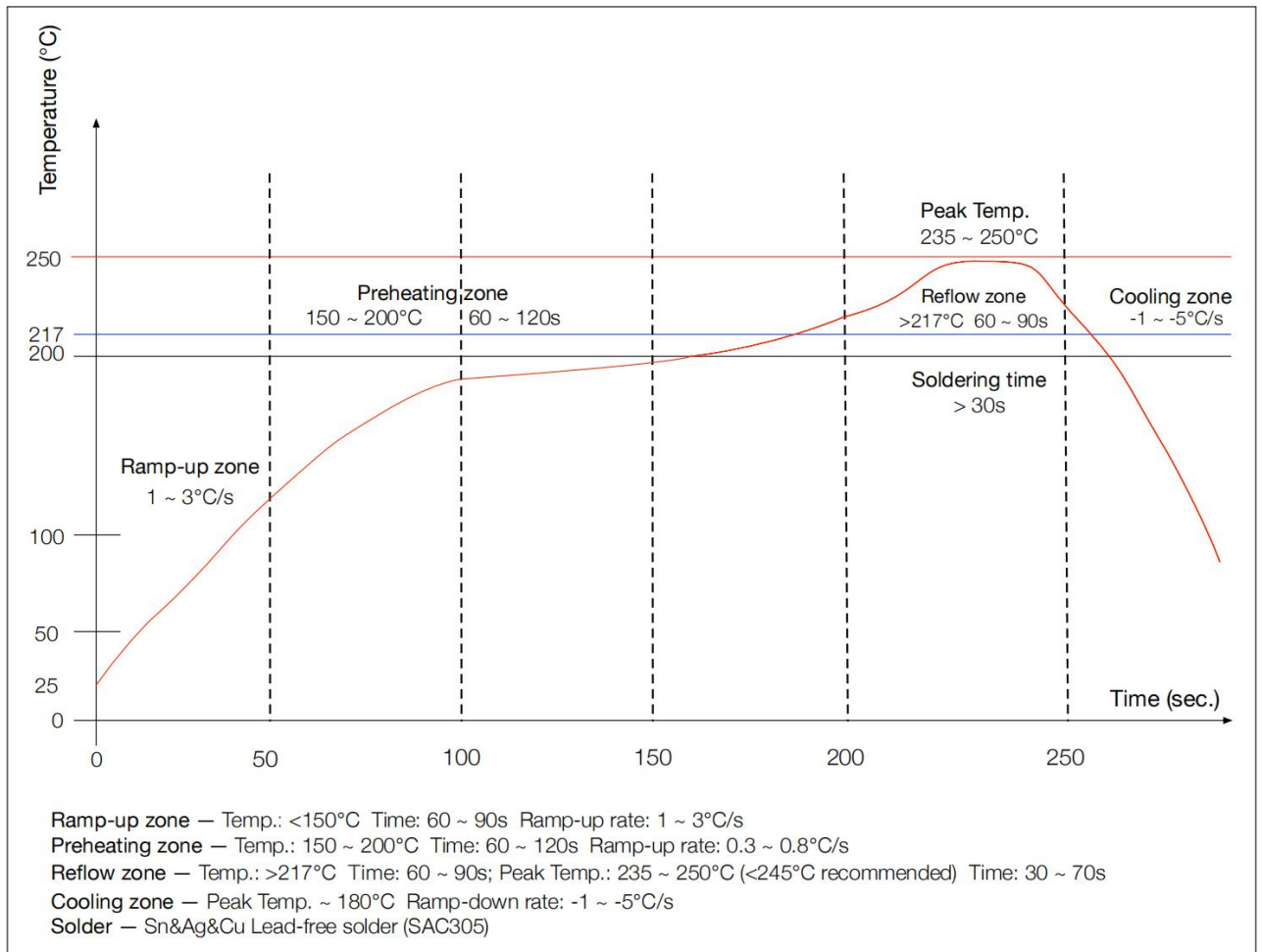
7.1 Absolute Maximum Ratings

Rating	Minimum	Maximum
Storage temperature	-40°C	+85°C

7.2 Recommended Operating Conditions

Operating Condition	Minimum	Maximum
Operating temperature range	-40°C	+85°C
Supply voltage: VBAT	+2.8V	+4.3V

8 Recommended reflow temperature profile



The module Must go through 125°C baking for at least 9 hours before SMT AND IR reflow process!

若拆封后未立即上线，天嘉润科技建议让下次上线前务必以 **125°C** 烘烤 **9** 小时以上！

Record of Changes

Data	Revision	Description
2021-08-03	V1.0	Original publication of this document.
2021-11-21	V1.1	Updata temperature.

IMPORTANT NOTICE

Sky Jiarun Technologies Co.,Ltd (SJR) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current. All products are sold subject to the SJR terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

SJR warrants performance of its products to specifications applicable at the time of sale in accordance with SJR's standard warranty. Testing and other quality control techniques are utilized to the extent SJR deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

In order to minimize risks associated with customer applications, adequate design and operating safeguards must be used by the customer to minimize inherent or procedural hazards. SJR products are not authorized for use as critical components in life support devices or systems without the express written approval of an officer of the company. Life support devices or systems are devices or systems that are intended for surgical implant into the body, or support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided, can be reasonably expected to result in a significant injury to the user. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

SJR assumes no liability for applications assistance or customer product design. SJR does not warrant or represent that any license, either express or implied, is granted under any patent right, mask work right, or other intellectual property right of SJR covering or relating or any combination, machine, or process in which such products or services might be or are used.

Tel: (0755) 85279490

Fax: (0755) 85279683

Web: www.tianjiarun.com

E-mail: sales@tianjiarun.com